

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claim 1. (currently amended) A method comprising:

adhering the active face of a singulated semiconductor die to a sacrificial carrier;  
encapsulating a backside of the singulated semiconductor die having a bond pad,  
and thereby forming a substantially rigid assembly structure;  
separating the assembly structure from the sacrificial carrier to expose the active  
face of the singulated semiconductor die;  
layering an insulating material over the active face of the singulated semiconductor  
die; and  
layering a conductive material over the insulating material, wherein a portion of the  
conductive material contacts at least one the die bond pad.

Claim 2. (original) The method of claim 1, wherein layering the insulating  
material further comprises creating at least one opening in the insulating material to  
expose at least one die bond pad.

Claim 3. (original) The method of claim 1, wherein layering the conductive  
material further comprises creating at least one conductive trace in the conductive  
material.

Claim 4. (original) The method of claim 3 further comprises creating a plurality  
of package terminals.

Claim 5. (original) The method of claim 1, wherein layering the insulating  
material over the active face of the singulated semiconductor die further comprises  
layering a material selected from a group consisting of polyimide,  
benzocyclobutene (BCB) and polybenzoxazole (PBO).

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Claim 6. (original) The method of claim 1, wherein layering the conductive material further comprises layering copper over the insulating material.

Claims 7-20 (canceled)

- Claim 21. (new) A method comprising:
- providing a semiconductor die having a active face, a back side and a bond pad;
- adhering the active face of the semiconductor die to a carrier;
- encapsulating the backside of the semiconductor die with an encapsulant;
- hardening the encapsulant;
- removing the carrier from the active face of the semiconductor die;
- applying a layer of insulating material over the active face of the semiconductor die; and
- applying a layer of conductive material over the insulating material, wherein a portion of the conductive material contacts the bond pad.
- Claim 22 (new) The method of claim 20, further comprising creating an opening through the layer of insulating material.
- Claim 23 (new) The method of claim 20, further comprising creating a conductive trace in the layer of conductive material and a package terminal.
- Claim 24 (new) The method of claim 20, wherein the insulating material includes a material selected from a group consisting of polyimide, benzocyclobutene (BCB) and polybenzoxazole (PBO).

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Claim 25. (new) A method comprising:

providing a semiconductor die having a active face, edge surfaces, a back side and a bond pad;

attaching the active face of the semiconductor die to a carrier;

encapsulating the backside and the edge surfaces of the semiconductor die with an encapsulant; and

hardening the encapsulant.

Claim 26 (new) A method comprising:

providing a semiconductor die having a active face, a back side and a bond pad;  
attaching the active face of the semiconductor die to a carrier;  
encapsulating the backside and the edge surfaces of the semiconductor die with an encapsulant;  
hardening the encapsulant to form a disk-shaped assembly structure;  
removing the carrier from the active face of the semiconductor die;  
forming a first layer of insulating material over the active face of the semiconductor die;  
forming an opening through the first layer of insulating material to uncover the bond pad;  
forming a layer of copper over the insulating material;  
forming a package terminal in the copper layer;  
forming a cooper trace with which the bond pad and the package terminal are electrically coupled; and  
applying a second layer of insulating material over the bond pad and the conductive trace.

Claim 27. (new) The method of claim 26, wherein the insulating material includes a material selected from a group consisting of polyimide, benzocyclobutene (BCB) and polybenzoxazole (PBO).